LNJ337W83RA

Hight Bright Surface Mounting Chip LED

ESS II Type

■ Absolute Maximum Ratings $T_a = 25°C$

Parameter	Symbol	Rating	Unit
Power dissipation	P_D	55	mW
Forward current	I_F	20	mA
Pulse forward current *	I_{FP}	60	mA
Reverse voltage	V_R	4	V
Operating ambient temperature	T_{opr}	–30 to +85	°C
Storage temperature	T_{stg}	–40 to +100	°C

Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

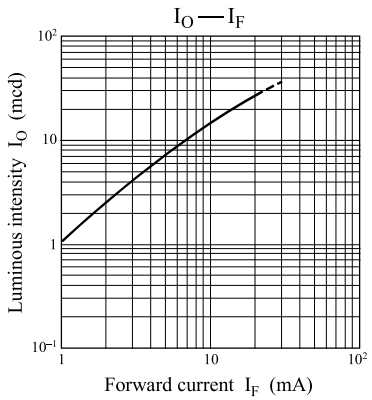
■ Lighting Color

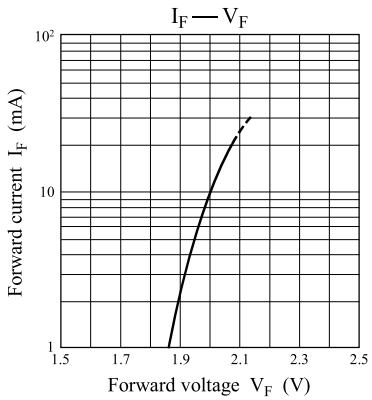
- Yellow Green

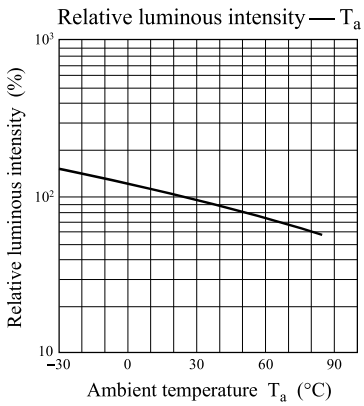
■ Electro-Optical Characteristics $T_a = 25°C \pm 3°C$

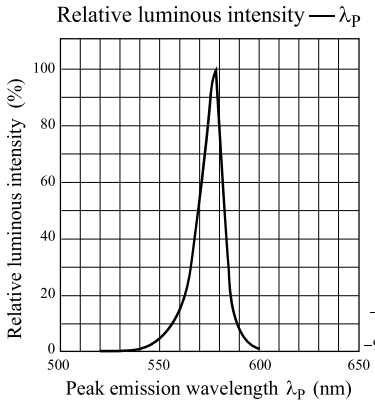
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity *1	I_O	$I_F = 5$ mA	4.0	7.5	28.0	mcd
Reverse current	I_R	$V_R = 4$ V			100	μA
Forward voltage	V_F	$I_F = 5$ mA		1.95	2.30	V
Peak emission wavelength	λ_P	$I_F = 5$ mA		575		nm
Dominant emission wavelength *2	λ_d	$I_F = 5$ mA	566	572	576	nm
Spectral half band width	$\Delta\lambda$	$I_F = 5$ mA		20		nm

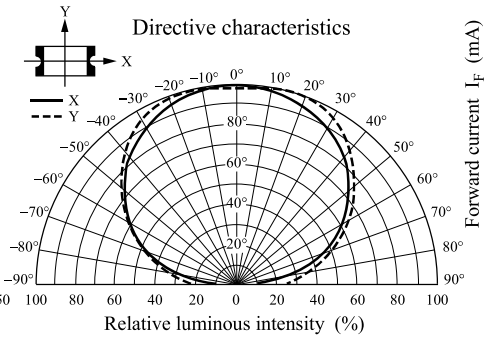
Note) *1: Measurement tolerance: ±20%
*2: Measurement tolerance: ±2 nm

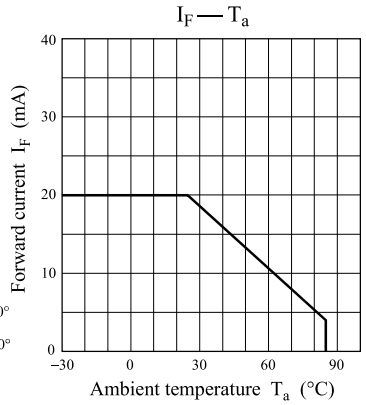




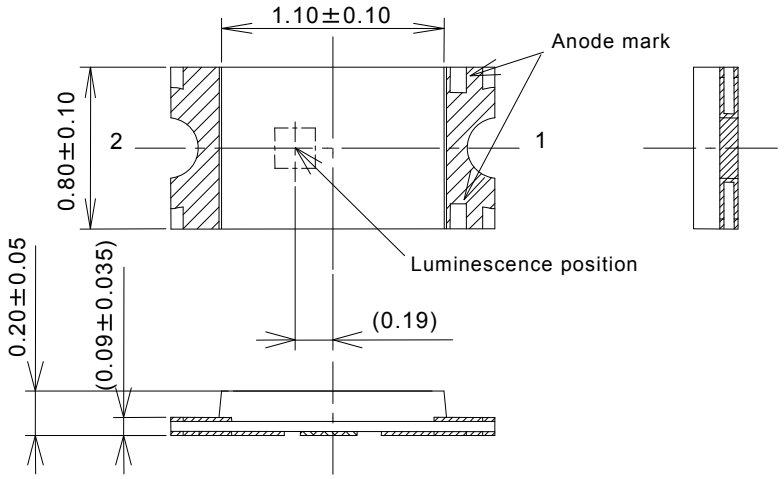


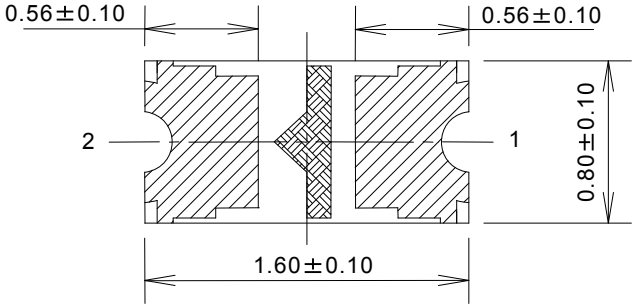


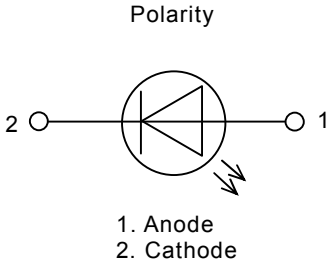




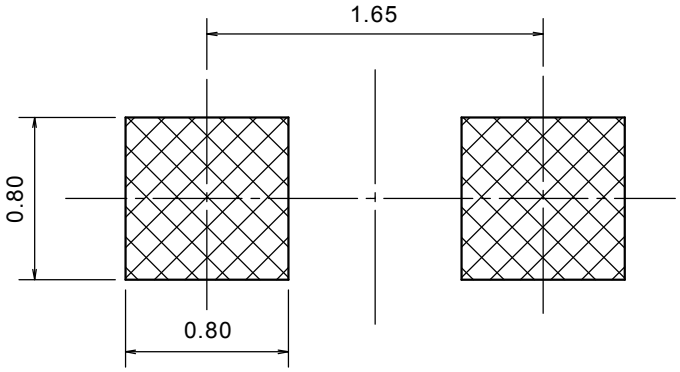
■ Package (Unit: mm)







Recommended Land Layout



(Note1)Electrode projection is not included in the package dimensions.
(Note2)About solder thickness, please examine the products yourself completely.
(Recommended thickness : t=0.10 mm～0.15 mm)

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No.020210

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